

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOSVI)

2SK4103

Switching Regulator Applications

- Low drain-source ON resistance: $R_{DS(ON)} = 1.35 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 2.8S$ (typ.)
- Low leakage current: $I_{DSS} = 100 \mu A$ ($V_{DS} = 500 V$)
- Enhancement model: $V_{th} = 2.0\sim 4.0 V$ ($V_{DS} = 10 V, I_D = 1 mA$)

Absolute Maximum Ratings ($T_a = 25^\circ C$)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	500	V
Drain-gate voltage ($R_{GS} = 20 k\Omega$)		V_{DGR}	500	V
Gate-source voltage		V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	5	A
	Pulse ($t = 1 ms$) (Note 1)	I_{DP}	20	
Drain power dissipation ($T_c = 25^\circ C$)		P_D	40	W
Single pulse avalanche energy (Note 2)		E_{AS}	180	mJ
Avalanche current		I_{AR}	5	A
Repetitive avalanche energy (Note 3)		E_{AR}	4	mJ
Channel temperature		T_{ch}	150	$^\circ C$
Storage temperature range		T_{stg}	-55~150	$^\circ C$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	3.125	$^\circ C/W$

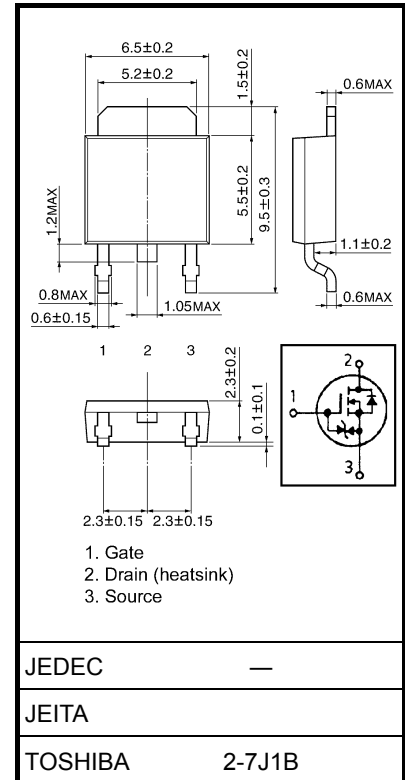
Note 1: Ensure that the channel temperature does not exceed $150^\circ C$ during use of the device.

Note 2: $V_{DD} = 90 V, T_{ch} = 25^\circ C$ (initial), $L = 12.2 mH, I_{AR} = 5 A, R_G = 25 \Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

Unit: mm



Weight: 0.36 g (typ.)

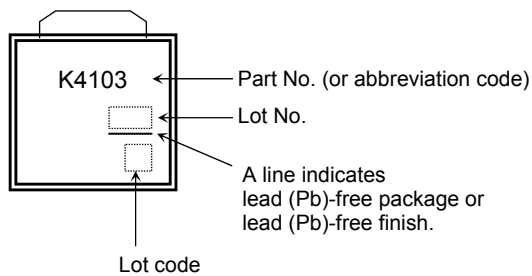
Electrical Characteristics (Ta = 25°C)

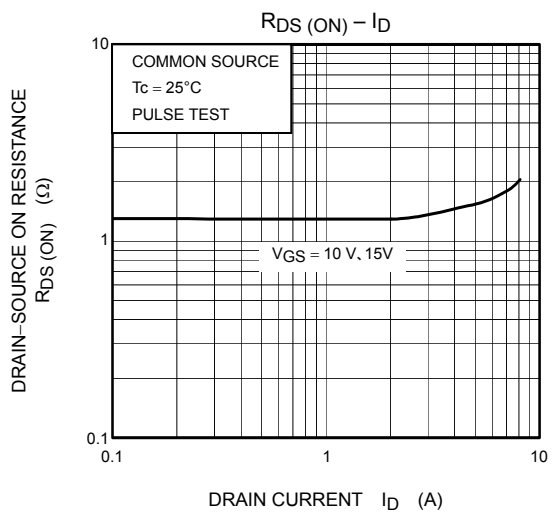
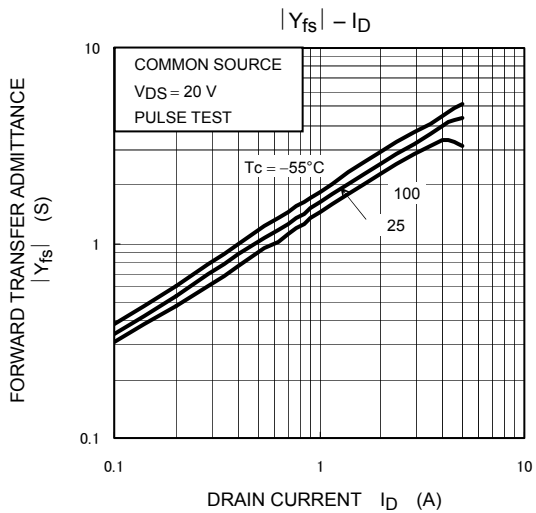
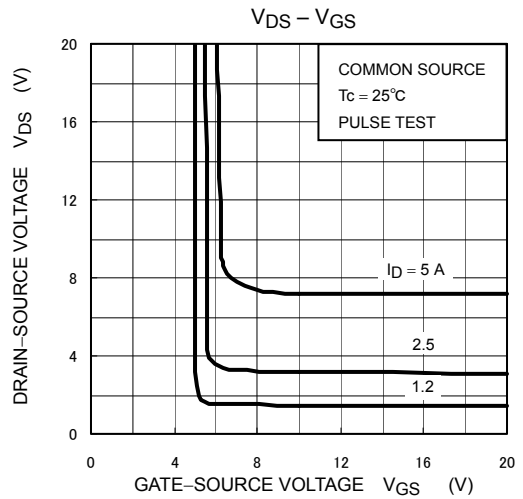
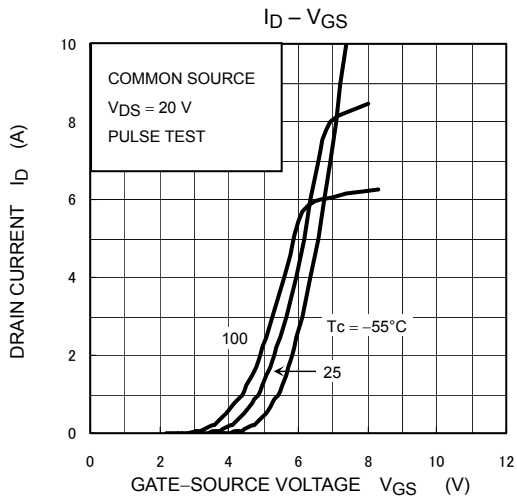
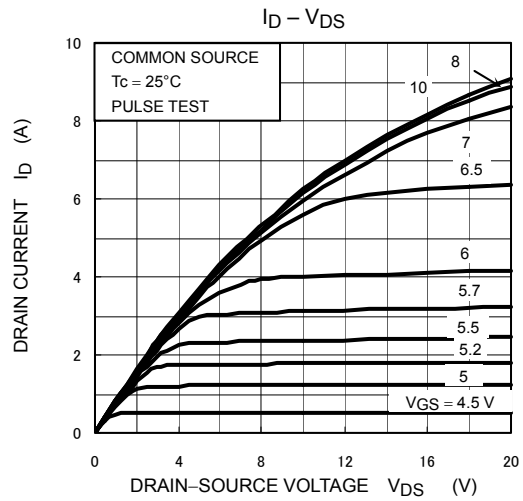
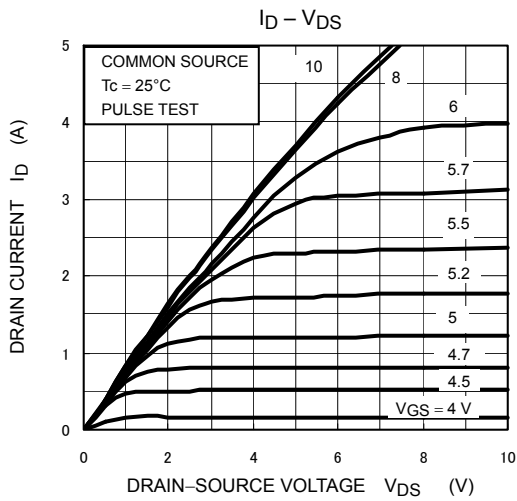
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	± 10	μA
Gate-source breakdown voltage		$V_{(BR)GSS}$	$I_D = \pm 10 \mu\text{A}, V_{GS} = 0 \text{ V}$	± 30	—	—	V
Drain cutoff current		I_{DSS}	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	500	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	2.0	—	4.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 10 \text{ V}, I_D = 2.0 \text{ A}$	—	1.35	1.50	Ω
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10 \text{ V}, I_D = 2.5 \text{ A}$	1.4	2.8	—	S
Input capacitance		C_{iss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	550	—	pF
Reverse transfer capacitance		C_{rss}		—	7	—	
Output capacitance		C_{oss}		—	70	—	
Switching time	Rise time	t_r	<p>V_{GS} 10 V, 0 V, $I_D = 2.5 \text{ A}$, V_{OUT}, $R_L = 90 \Omega$, $V_{DD} \approx 225 \text{ V}$, Duty $\leq 1\%$, $t_w = 10 \mu\text{s}$</p>	—	10	—	ns
	Turn-on time	t_{on}		—	20	—	
	Fall time	t_f		—	10	—	
	Turn-off time	t_{off}		—	50	—	
Total gate charge		Q_g	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	—	16	—	nC
Gate-source charge		Q_{gs}		—	10	—	
Gate-drain charge		Q_{gd}		—	6	—	

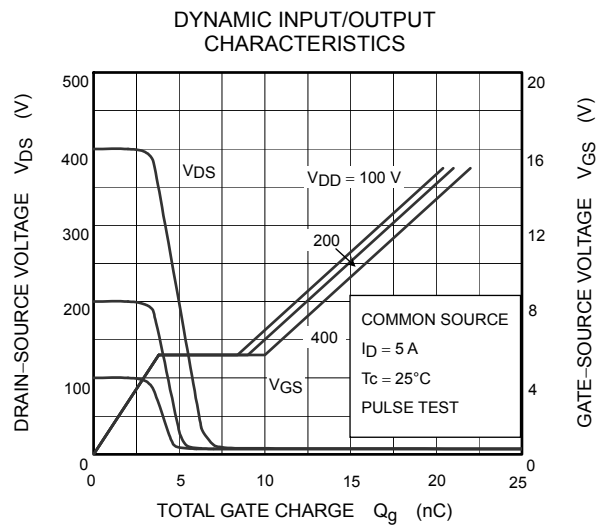
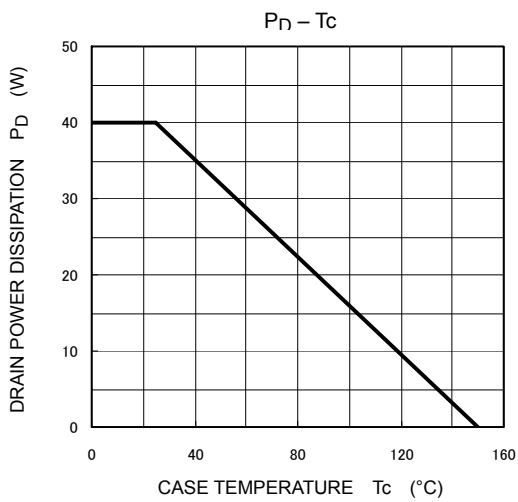
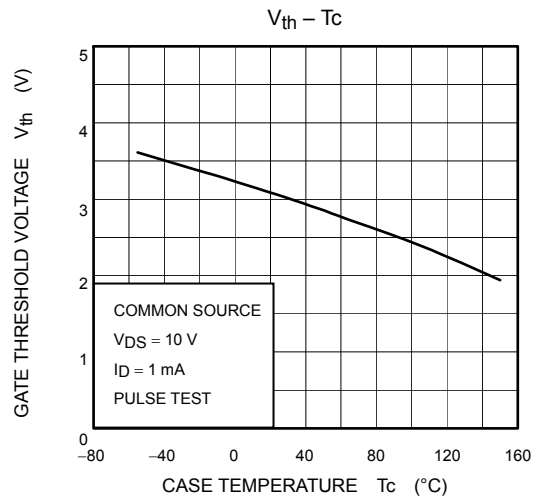
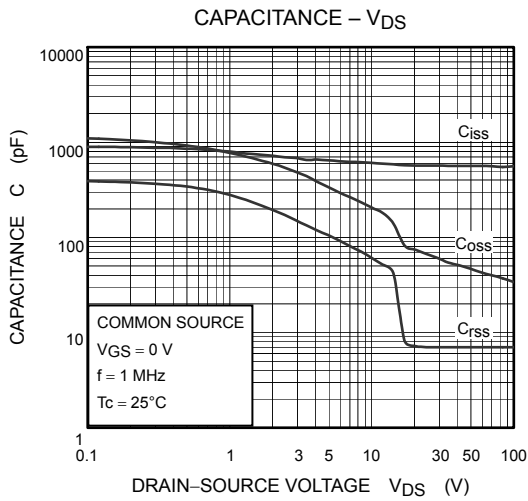
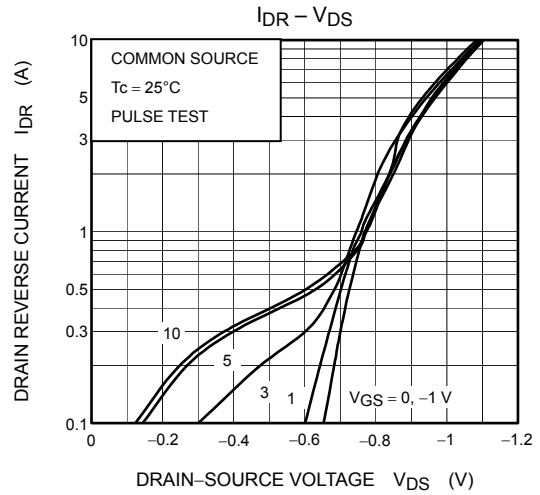
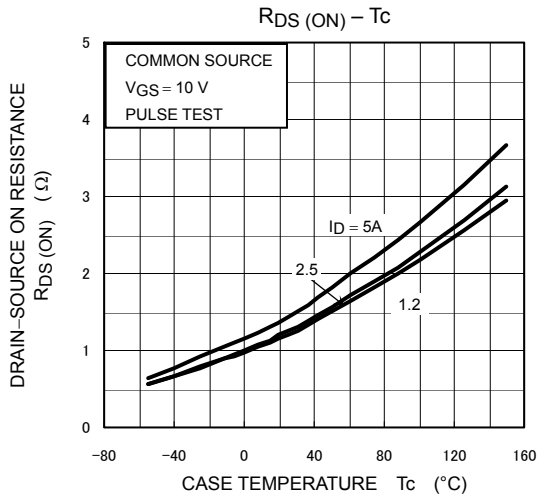
Source-Drain Ratings and Characteristics (Ta = 25°C)

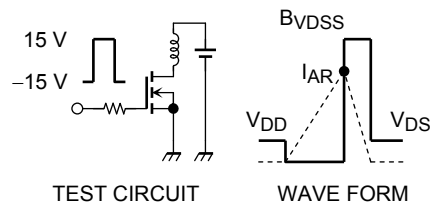
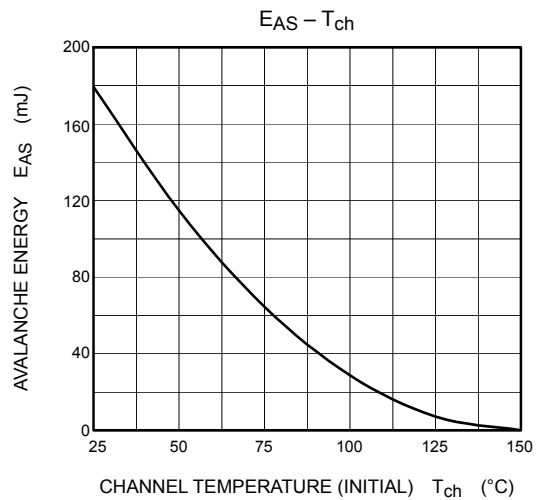
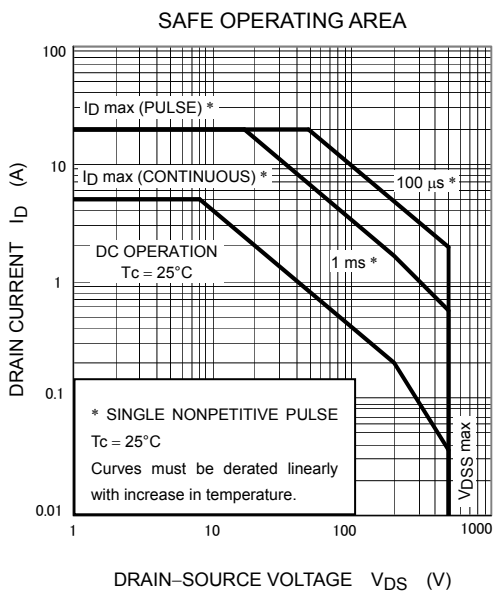
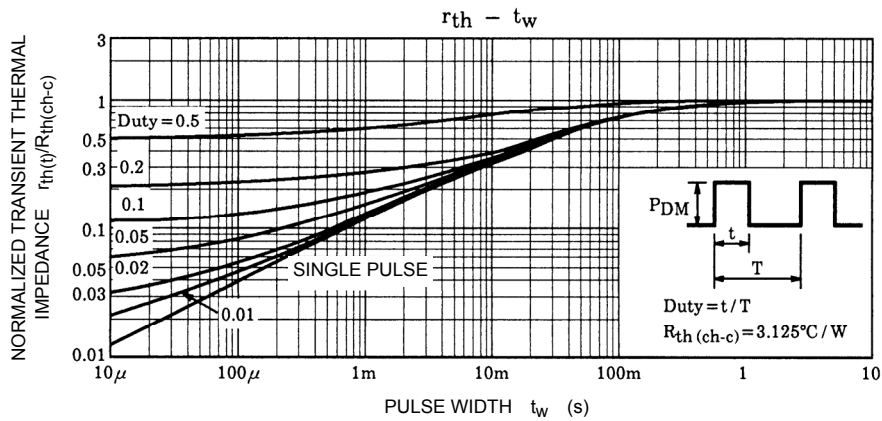
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)		I_{DR}	—	—	—	5	A
Pulse drain reverse current (Note 1)		I_{DRP}	—	—	—	20	A
Forward voltage (diode)		V_{DSF}	$I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-1.7	V
Reverse recovery time		t_{rr}	$I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V},$	—	1400	—	ns
Reverse recovery charge		Q_{rr}	$dI_{DR}/dt = 100 \text{ A}/\mu\text{s}$	—	9	—	μC

Marking









$R_G = 25 \Omega$
 $V_{DD} = 90 \text{ V}, L = 12.2 \text{ mH}$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - V_{DD}} \right)$$

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